

ABSTRACT

A method for packaging and singulating a wafer having a plurality of micro devices includes providing a multi-lid substrate having a trench having intersection portions and non-intersection portions formed on a first side of the multi-lid substrate. The
5 multi-lid substrate is coupled to the wafer such that the intersection portions of the trench pattern extend adjacent to at least three micro devices. Portions of the multi-lid substrate between a second side of the multi-lid substrate and the trench pattern are removed while the multi-lid substrate is coupled to the wafer.